

# Mithril - FMCW Radar

by

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# Chapter 1

## Introduction

The following includes small biographies on all the authors as well as their research interests and projects.

### Authors' Biographies

#### Ajay Thakkar

**Ajay Thakkar** Ajay Thakkar is a junior majoring in Computer Engineering. He is interested in signal processing and lower level coding. Below you can find his GitHub: <https://github.com/athakkar2>.

#### Tomas Esson

**Tomas Esson** is an aspiring Computer Engineering at Stevens Institute of technology. He is an avid surfer and enjoys elegant math proofs. Currently pursuing interests in computer chip design, digital systems implementation, mathematical optimization of computer chips, and electrical engineering.

#### Juan Jimenez

**Juan Jimenez** is a Junior Computer Engineering student at the Stevens Institute of technology. Interested in the intersection between Artificial Intelligence, embedded electronics, and software engineering. To see more projects visit the following GitHub link: <https://github.com/jjimene1>

# Chapter 2

## Project Description

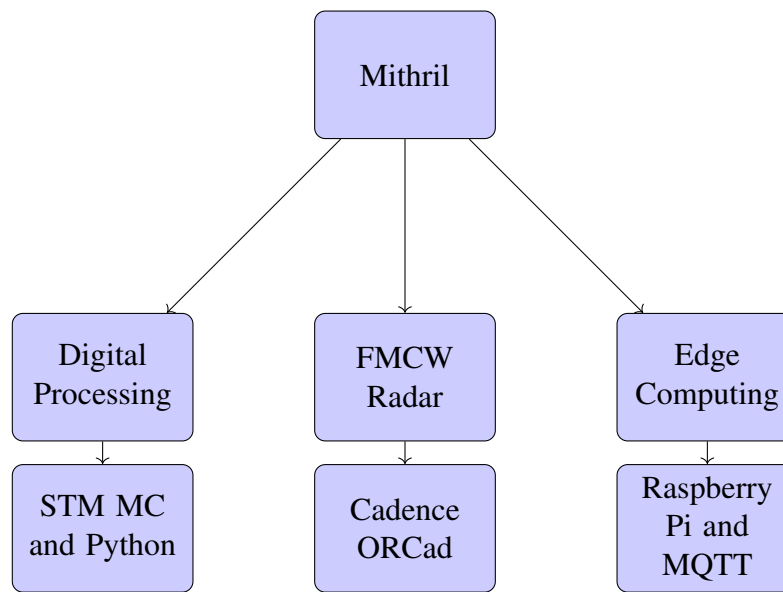


Figure 2.1: Flowchart of the Mithril system

Mithril is a nodal FMCW radar system that incorporates traditional FMCW radar, digital processing, edge computing, and distributed networking. The initial application of this project was for a military context. State of the art missile defense systems cost too much and are too big to be viable in many places, and while our system doesn't compare to systems like the Iron Dome or Patriot System it could allow for at least an alert for civilians to leave possible shelling and bombing sites. The system would include small radar nodes capable of detecting missiles and electronically steering their line of sight via phased array antennas. Multiple nodes could work in tandem to communicate their findings, allowing for a wider range of sight and active tracking of projectiles. The network would be able to function regardless of how many nodes there were, and still continue to function if nodes are destroyed.

As can be seen in Figure 2.1, the radar was designed as a standalone PCB in ORCad, digital processing was handled by STM microcontrollers, and distributed networking is done via Raspberry



Pi's and the MQTT protocol. All of these components were designed, engineered, and interfaced from scratch with a limited budget of 2000 dollars.

## 2.1 FMCW Radar PCB

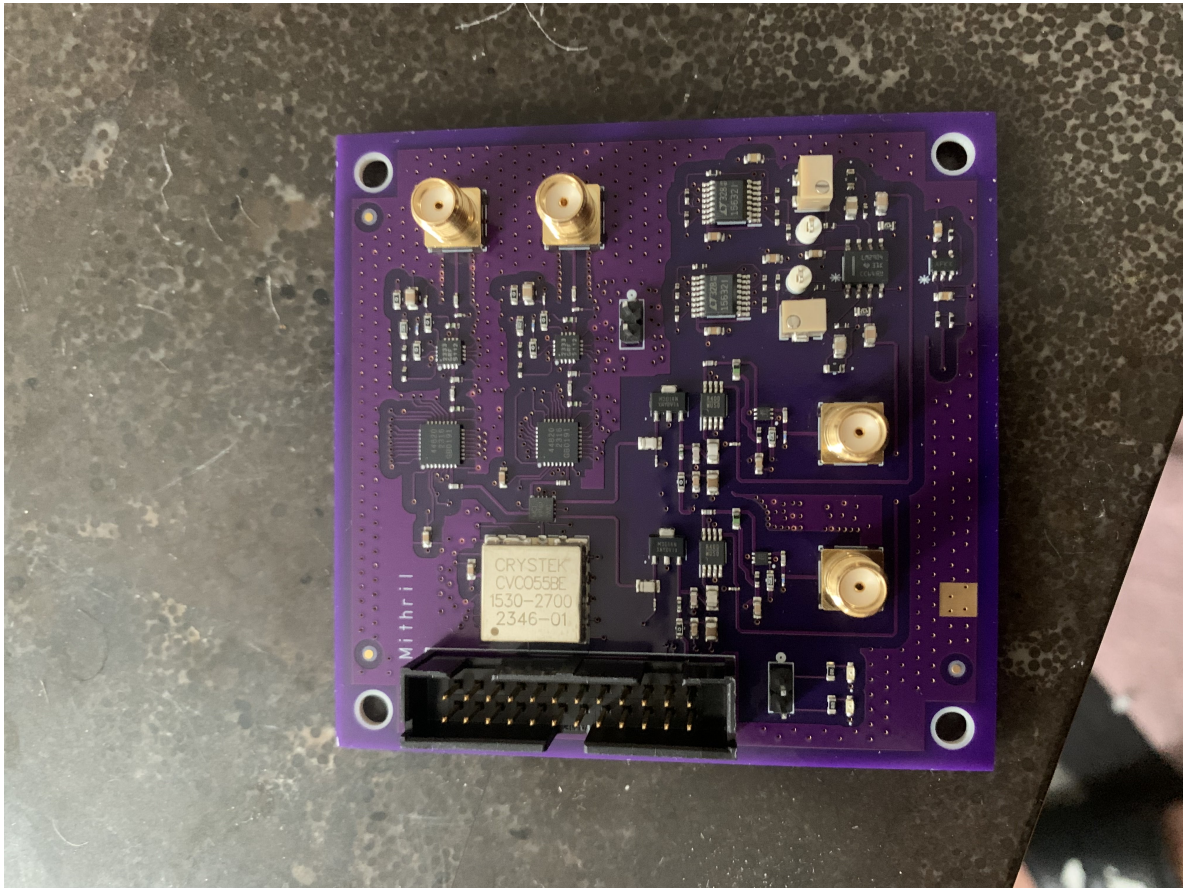


Figure 2.2: Mithril PCB

The heart of the project is a standalone PCB capable of FMCW radar and phased array beamforming, which can be seen in Image 2.2. The PCB has a transmitting and receiving portion, each with several stages. The TX portion has a stage for signal synthesis, phase shifting, and amplification. The RX portion has a stage for amplification, mixing, and baseband filtering/amplifying. There are also GPIO pins for interfacing with the microcontroller, as well as test pins for analyzing the signals we receive. This was foreign ground for the entire team, and was started by first researching common RF chains, picking parts that could handle the aforementioned stages, designing the schematic and layout in ORCad, and then printing and assembling the board. Afterwards, we tested for weeks to find different issues and workarounds which will be mentioned later.

## 2.2 Digital Processing

The digital processing was handled entirely by the [STM-F756ZG](#). Two of them were used in the final implementation, where one was responsible for generating a ramp voltage which will be discussed later, and the other responsible for sampling the radar's received signal, windowing the signal, taking the FFT, transmitting the FFT over UART, and receiving commands over UART to program the phase shifter on the PCB via its GPIO pins. This was a lot of tasks, and all of it was programmed to run in a superloop with the help of DMA and interrupts.

## 2.3 Networking

How the fuck does a mesh network work borger.

## **Chapter 3**

## **Resources**

# **Chapter 4**

## **Radar Theory**

### **4.1 Getting Started**

include the benefits of using higher frequency signals  
heterodyning

# Chapter 5

## Part Selection

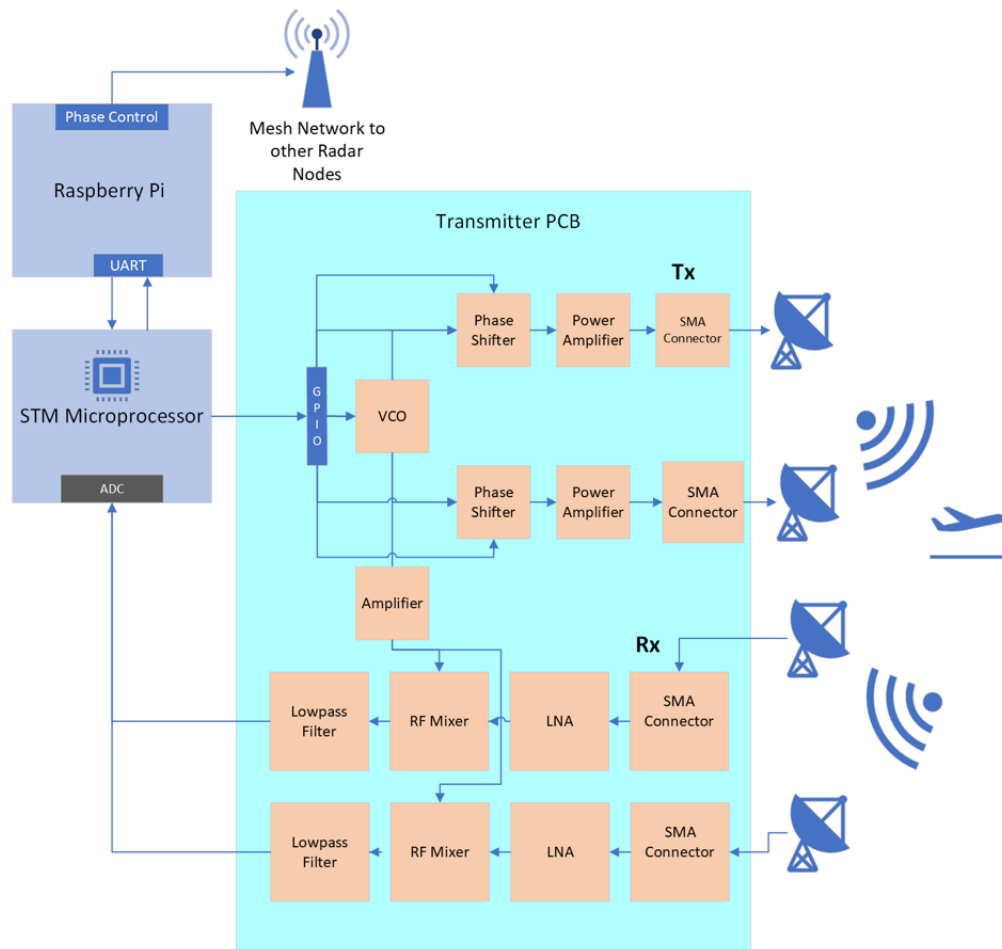


Figure 5.1: Architecture Overview

In this chapter, we will go through the architecture of the PCB and show what parts we picked and what purposes they serve. Figure 5.1 shows the overall architecture of the project.

## 5.1 Voltage Controlled Oscillator (VCO)

The first step in creating a radar is signal synthesis. You essentially need to create an alternating current signal that can go through your antenna and radiate out into the air. To reiterate from Chapter 4, higher frequency signals are important for a better radar resolution, and so it is desired to have a signal that is high in frequency. Naively, at the beginning of this project we thought we could use a 16 bit DAC to synthesize our signal but after finding out its max clock rate was 1 MHz, we realized a DAC was not fit for this. All we needed was something that could create a simple sinusoid at a very high frequency.

Voltage Controlled Oscillators (VCO) do just this. They take in a "tuning voltage" which corresponds to a certain frequency of sinusoid which it will output. The circuitry for this is beyond me, but for a good overall guide on VCOs you can check out DigiKey's article [here](#).

Now that we knew how to synthesize our signal, it was important to find a good VCO that had a high output bandwidth. Whatever bandwidth the VCO has will impact what parts we can get in the other stages of the RF chain since these must be within the VCOs operating regions.

PERFORMANCE SPECIFICATION	MIN	TYP	MAX	UNITS
Lower Frequency:			1530	MHz
Upper Frequency:	2700			MHz
Tuning Voltage:	0.5		10.5	VDC
Supply Voltage:	4.75	5.0	5.25	VDC
Output Power:	+4.0	+7.5	+11.0	dBm
Supply Current:		15	30	mA
Harmonic Suppression (2 <sup>nd</sup> Harmonic):		-15		dBc
Pushing:			25.0	MHz/V
Pulling, all Phases:			35.0	MHz pk-pk
Tuning Sensitivity:		140		MHz/V
Phase Noise @ 10kHz offset:		-87		dBc/Hz
Phase Noise @ 100kHz offset:		-110		dBc/Hz
Load Impedance:		50		$\Omega$
Input Capacitance:			50	pF
Operating Temperature Range:	-40		+75	°C
Storage Temperature Range:	-45		+90	°C

Figure 5.2: VCO Datasheet Table

## Tuning Curve (Typical)

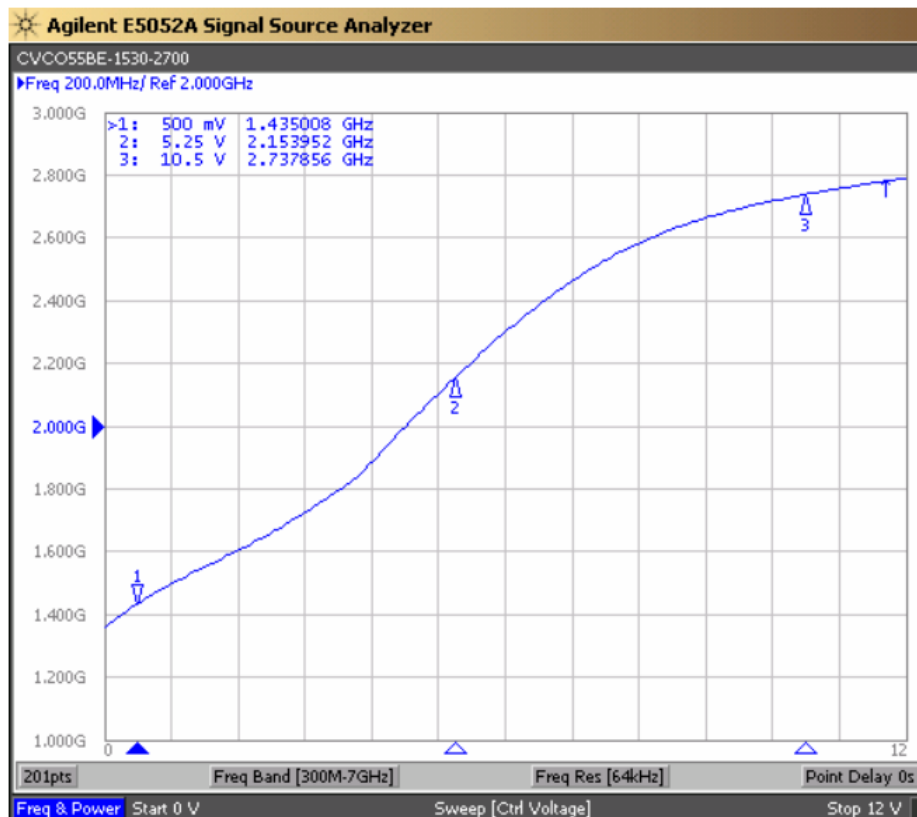


Figure 5.3: Tuning Voltage Graph

We chose a VCO from Crystek which can be found on Digikey [here](#). Looking at the specifications table in Figure 5.2, some good things to look for are first and foremost the frequency range of the part. It goes from about 1.5-2.7 GHz, which is a pretty wide range and would support a lot of other parts as it also covers the Wi-Fi band. The second thing to look for is output power. The output power can be a constraint for other parts, since they might have an absolute limit on their input power, and it is useful to know the output power for finding out how strong your signal will be once it propagates out of your antenna. Here we can see the output power is around 7.5 dBm, and this will be split four ways. Decibels are a logarithmic scale, so we cannot just divide by four but instead use a decibel calculator like [this one](#).

Now, another key metric is the tuning voltage. Luckily, this Crystek provides a tuning voltage graph found in Figure 5.3 that shows us how the output frequency changes with changes in the tuning voltage. One observation is that it is not linear, meaning our ramp voltage will not result in a true linear ramp in frequency. Another observation is that our chosen frequency of 1.8 GHz is around 3.5 volts following the graph. Our STM board that will generate the ramp voltage can by default only go to 3.3 volts, but we found a workaround to go to 5 volts which allowed us to stick with our decided center frequency.

## 5.2 Power Divider

As mentioned before, we want to divide the VCO's signal four ways because we want it to go to two phase shifters, and two mixers. At first we thought it was as simple as having one wire split into four, but as we will go over in Chapter 6, impedance matching is very important in RF circuits. To put it simply, impedance matching ensures that no power is reflected, and this is important because reflected power means distortions in the signal and power loss. That means we needed a power splitter meant for splitting an RF signal without causing reflected power. There is not much of note with the part we used which can be found [here](#). The main thing is that it contains the frequency of 1.8 GHz we want to use.

## 5.3 Phase Shifter

Two of the power dividers split paths will go into phase shifters. The phase shifters are used to make our phased array of antennas as explained in Chapter 4. They are able to change the phase (add time delay), to the signal so that when they propagate through the air they can construct and destruct. The phase shifters we chose can be found [here](#). These are digital phase shifters that have 256 different phases it can apply to the signal. They have a parallel or serial interface we can use to transmit 8 bit words That will alter the phase of our signal. The interface and its timing diagrams will be explained more in detail in Chapter 7. All we need to know is that the bandwidth that the chip supports contains 1.8 GHz.



## 5.4 Power Amplifier

### Nominal Operating Parameters – RF (1710 to 1920 MHz)

The following conditions apply unless noted otherwise: Typical Application Schematic using the 1710 to 1920 MHz tuning set,  $M1 = 6.0\text{ k}\Omega$ ,  $V_{DD} = 5\text{ V}$ ,  $I_{DDQ} = 212\text{ mA}$ ,  $50\text{ }\Omega$  system impedance,  $P_{OUT} = +21\text{ dBm}$ ,  $F_{TEST} = 1805\text{ MHz}$ ,  $T_{PKG\text{ HEAT SINK}} = 25\text{ }^{\circ}\text{C}$ . Evaluation board losses are included within the specifications.

Parameter	Symbol	Specification			Unit	Condition
		Min.	Typ.	Max.		
Small Signal Gain	S21		17.1		dB	$F_{TEST} = 1805\text{ MHz}$ , $T_{PKG\text{ HEAT SINK}} = 25\text{ }^{\circ}\text{C}$ , $V_{DD} = 5\text{ V}$ , $P_{IN} = -25\text{ dBm}$ .
Input Return Loss	S11		< -11		dB	$F_{RF} = 1710\text{ to }1920\text{ MHz}$ Small Signal.
Output Return Loss	S22		< -6		dB	$F_{RF} = 1710\text{ to }1920\text{ MHz}$ Small Signal.
Reverse Isolation	S12		< -21		dB	$F_{RF} = 1710\text{ to }1920\text{ MHz}$ Small Signal.
Noise Figure	NF		1.7		dB	On standard evaluation board.
Output 3rd Order Intercept Point	OIP3		40		dBm	18 dBm $P_{OUT}$ per Tone at 600 kHz Spacing.
Output 1 dB Compression Power	OP1dB		32.2		dBm	Sine wave input, $V_{DD} = 5\text{ V}$ , $T_{PKG\text{ HEAT SINK}} = 25\text{ }^{\circ}\text{C}$ .
Adjacent Channel Leakage Ratio	ACLR		-45		dBc	$P_{OUT} = +20\text{ dBm}$ , LTE 20MHz 100RB TM1.1 Downlink Waveform with 9.6dB PAR, $F_{TEST} = 1805\text{ MHz}$ , $T_{PKG\text{ HEAT SINK}} = 25\text{ }^{\circ}\text{C}$ , $V_{DD} = 5\text{ V}$ .

Figure 5.4: Power Amplifier Table

At this point after the VCO and phase shifter, we want the RF signal to propagate through the air. However, according to the radar range equation the power of the signal when attenuating through the air attenuates at a power of four which is a lot. Therefore, we need to make sure our signal is powerful enough to go pretty far. So, we use an RF power amplifier to amplify the signal. We chose a part from GuerillaRF which can be found [here](#). Looking at the table in Figure 5.4, we can see some key metrics when looking at power amplifiers. First, of course we want to make sure it has a bandwidth that supports our chosen frequency of 1.8 GHz. Second, we want to look at the small-signal gain and Output 1 dB Compression Point or OP1dB. The small-signal gain is the ideal gain that can be reached with a low power signal, and is listed as 17.1 dB. The OP1dB is a metric we did not know about and were thankful to find it. With most amplifiers, gain operates linearly meaning whatever power your input signal is you just add the gain of the amplifier and this will be the resulting power of the signal. However, at a certain point the amplifier saturates and does not operate linearly anymore, and will essentially cap-off its gain at the OP1dB limit. For example, with the OP1dB being 32.2 dB, if I input a signal that was 30 dB I would expect a resulting signal of 47.1 dB but this would not be the case. The amplifier ceases to operate linearly after the 32.2 dB mark, and will both distort the signal and output something weaker than expected. A lot of amplifiers will boast a high gain but have a low OP1dB, so this is definitely something to check for.

## 5.5 Low Noise Amplifier

### Nominal Operating Parameters - RF

The following conditions apply unless noted otherwise: typical measurement schematic using the 0.1 to 2.7 GHz tuning set,  $V_{DD} = 5\text{ V}$ ,  $V_{ENABLE} = 5\text{ V}$ ,  $I_{DDQ} = 60\text{ mA}$ ,  $F_{TEST} = 1.95\text{ GHz}$ ,  $50\ \Omega$  system impedance,  $T_{PKG\ BASE} = 25\text{ }^{\circ}\text{C}$ . Evaluation board losses are included within the specifications.

Parameter	Symbol	Specification			Unit	Condition
		Min.	Typ.	Max.		
Gain	S21	26.5	28		dB	
Noise Figure	NF		0.6	0.8	dB	On standard evaluation board.
Output 3rd Order Intercept Point	OIP3		31		dBm	+2 dBm $P_{OUT}$ per tone at 2 MHz spacing (1949 and 1951 MHz)
Output 1 dB Compression Power	OP1dB	18	20		dBm	

Figure 5.5: Low-Noise Amplifier Table

This is the first part that will be placed in the receiver RF chain. According to the Friis equation in Chapter 4, the first stage in the receiver RF chain matters a lot for the noise figure of your system. Therefore, we wanted to find a part with a low noise figure and high gain, as this will impact our SNR the most. Low noise amplifiers are made for this exact purpose, where they amplify a small signal with very low noise. The part we chose was [this](#), which is made by GuerillaRF. By examining the table in Figure 5.5, we can see that it has a gain of 28 dB, and a noise figure of .6 dB. We also can look at the OP1dB which has a figure of 20 dB. Since the LNA will be amplifying a signal straight from an antenna, the signal will be super weak and there is a low likelihood it will reach the OP1dB.

## 5.6 Mixer/LO Amp

### Electrical Specifications, $T_A = +25^\circ\text{C}$ , LO = +17 dBm, IF = 200 MHz\*

Parameter	Min.	Typ.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.	Units
Frequency Range, RF		1.7 - 1.8		1.8 - 2.0			2.0 - 2.2			GHz
Frequency Range, LO		1.4 - 1.75		1.5 - 1.95			1.7 - 2.15			GHz
Frequency Range, IF		DC - 300		DC - 300			DC - 300			MHz
Conversion Loss		9	11		8.8	10.5		8.8	10.5	dB
Noise Figure (SSB)		9	11		8.8	10.5		8.8	10.5	dB
LO to RF Isolation	29	33		24	30		20	25		dB
LO to IF Isolation	16	20		17	22		19	25		dB
IP3 (Input)	30	34		32	36		28	32		dBm
1 dB Gain Compression (Input)	18	21		18	21		18	22		dBm
LO Input Drive Level (Typical)		+16 to +18		+16 to +18			+16 to +18			dBm

\*Unless otherwise noted, all measurements performed as a downconverter, with low side LO & IF = 200 MHz.

Figure 5.6: Mixer Table

### Harmonics of LO

LO Freq (GHz)	nLO Spur @ RF Port			
	1	2	3	4
1.4	42	26	56	46
1.55	33	25	56	53
1.7	29	29	49	50
1.85	26	31	44	53
2	24	36	44	48
2.15	21	38	43	49

LO = +17 dBm  
All values are in dBc below input LO level @ RF port.

Figure 5.7: Mixer Harmonics Table

Now that our received signal is amplified we must down-convert it in order to sample and process it. The process for doing this is called heterodyning or mixing, and the theory behind this can be found in detail in Chapter 4. A mixer has three ports, the local oscillator, RF signal, and output. The local oscillator and RF signal are multiplied to produce the sum and difference of the LO and RF signals on the output port. We are mainly interested in the difference, also called the Intermediate Frequency (IF) since it is a low frequency and can be sampled easily. In our case, we take a copy of the VCO as the local oscillator and then mix this with the amplified return signal to produce our intermediate frequency. To achieve this, we used a discontinued mixer from Analog Devices which can be found [here](#). Looking at the mixer's specifications table in Figure 5.6, we can see some new properties. The conversion loss is the output IF power delivered minus the available RF input signal power. The LO to RF Isolation is how much of the local oscillator signal leaks into

the RF port, and the LO to IF Isolation is how much the local oscillator signal leaks into the output port. This is a passive component, meaning it does not require power and solely operates off the power of the LO and RF signals. Therefore we see in the table that the LO Input must be 16-18 dBm to drive the mixer. Essentially the local oscillator powers the mixer, and its harmonics will therefore be prominent in the IF port due to leakage. We can see in Figure 5.7 that at 1.85 GHz the manufacturer tells us the strength of LO harmonics up to the fourth order. At the top it says spur which means spurious (unwanted) outputs due to the nonlinearity of the mixer. Essentially this table tells us that there will be unwanted spectral components in the output, which is something we did not pay enough attention to and will discuss in Chapter 10.

**Table 1. Typical Performance <sup>(1)</sup>**

Characteristic	Symbol	900 MHz	2140 MHz	3500 MHz	Unit
Small-Signal Gain (S21)	G <sub>p</sub>	19.5	15	10	dB
Input Return Loss (S11)	IRL	-25	-12	-8	dB
Output Return Loss (S22)	ORL	-11	-13	-19	dB
Power Output @1dB Compression	P1dB	25	25.8	25	dBm
Third Order Output Intercept Point	OIP3	40.5	40.5	40	dBm

1. V<sub>CC</sub> = 5 Vdc, T<sub>A</sub> = 25°C, 50 ohm system, application circuit tuned for specified frequency.

Figure 5.8: LO Amp Table

As we said before, the mixer is a passive component which is driven by the LO which needs a power level of 16-18 dBm. After splitting our VCO's output four ways, we have about a 2 dBm signal that we must amplify. So, we chose an RF broadband amplifier from NXP which can be found [here](#). As we can see in Figure 5.8, the amp has a gain of around 15 dB for our frequency and an OP1dB of 25.8 dB which is a lot of headroom.

## 5.7 IF Amplifiers and Filters

Now, our return signal has been downconverted, but the power of that signal is very weak. As well as this, there are unwanted spectral components in that signal that are bi-products of the mixer that we need to get rid of. This means we need amplifiers and filters to make our signal ready to be sampled and processed in the microcontroller. First we used a super simple op-amp that served as a voltage follower which can be found [here](#). This was used to create a virtual ground for our biasing. Then we use a dual channel op-amp from TI for our variable gain amplifier which can be found [here](#).

OUTPUT						
$V_O$	Voltage output swing from rail	Positive rail (V+)		$I_{OUT} = 50 \mu A$	1.35	1.42
				$I_{OUT} = 1 mA$	1.4	1.48
				$I_{OUT} = 5 mA^{(1)}$	1.5	1.61
		Negative rail (V-)		$I_{OUT} = 50 \mu A$	100	150
				$I_{OUT} = 1 mA$	0.75	1
				$V_S = 5 V, R_L \leq 10 k\Omega$ connected to (V-) $T_A = -40^\circ C$ to $+85^\circ C$	5	20

Figure 5.9: Output Swing Characteristics

Honestly, when selecting parts we figured all operational amplifiers just acted the same way. However, after printing and manufacturing we ran into problems which will be discussed in Chapter 10 that could have been remedied if we paid more attention to the Op-Amps we were using. The main problem is that these operational amplifiers are not "Rail-to-Rail". While rail-to-rail amplifiers guarantee that they do not saturate until the positive and negative voltages you've supplied it, other amplifiers have what is called voltage swing. As we can see in Figure 5.9, the range of voltage that the operational amplifier can achieve is not its rails, but specifies how much lower than its rail it will be. This is something to look out for when selecting an Op-Amp.

- **Extremely Easy to Use—A Single Resistor Value Sets the Cutoff Frequency ( $256Hz < f_C < 256kHz$ )**
- **Extremely Flexible—Different Resistor Values Allow Arbitrary Transfer Functions with or without Gain ( $256Hz < f_C < 256kHz$ )**
- Supports Cutoff Frequencies Up to 360kHz Using FilterCAD™
- LTC1563-2: Unity-Gain Butterworth Response Uses a Single Resistor Value, Different Resistor Values Allow Other Responses with or without Gain
- LTC1563-3: Unity-Gain Bessel Response Uses a Single Resistor Value, Different Resistor Values Allow Other Responses with or without Gain
- Rail-to-Rail Input and Output Voltages
- Operates from a Single 3V (2.7V Min) to  $\pm 5V$  Supply
- Low Noise:  $36\mu V_{RMS}$  for  $f_C = 25.6kHz$ ,  $60\mu V_{RMS}$  for  $f_C = 256kHz$
- $f_C$  Accuracy  $< \pm 2\%$  (Typ)
- DC Offset  $< 1mV$
- Cascadable to Form 8th Order Lowpass Filters
- Available in Narrow SSOP-16 Package

Figure 5.10: Filter Features

After amplifying the signal, we wanted to filter out unwanted spectral components by using a strong filter. Instead of designing this ourselves, we decided to use a 4th Order LPF which can be found [here](#). By looking at Figure 5.10, we can see that this is an integrated circuit with a flexible cutoff frequency. It also says that it is a rail-to-rail input and output circuit, which is an important

feature to note as discussed with the amplifiers. A fourth order filter just means that this filter has four filters with the same cutoff frequency cascaded upon each other, which yields a steeper frequency response and attenuates are unwanted signals further.

# PCB

## 6.1 Schematic

### 6.1.1 ORCad Capture Overview

ORCad comes with a schematic software called Capture CIS which we used to create our schematics. As a reference to both us and others, this section is dedicated to providing a small walkthrough to using the software and some nice-to-know features.

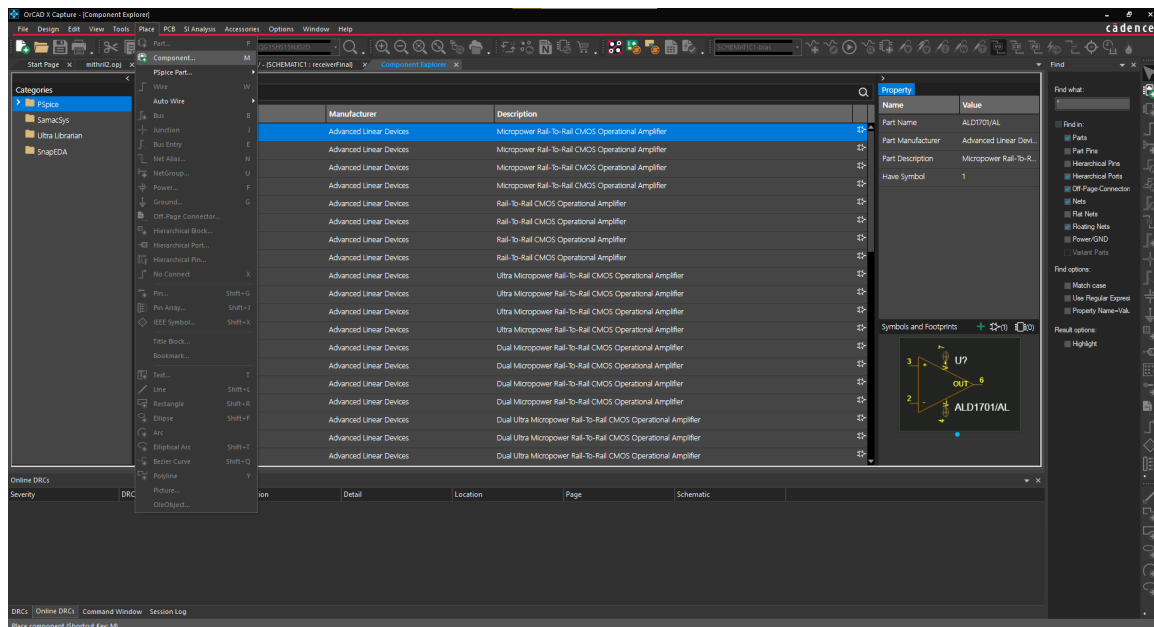


Figure 6.1: Component Database Search

The first important feature we found was the component database, which can be seen in Figure 6.1. By clicking on the icon that has a small chip and cloud will take you to this page which contains subdirectories "PSpice" "SamacSys" "UltraLibrarian" and "SnapEDA". PSpice contains parts that have simulation properties, but we ignored this as we did not know how to use PSpice.

The other three are different databases containing schematic symbols and layout footprints for parts that can be found on major retailers like DigiKey, Mouser, and Arrow.

...	SI8645BB-B-IS	Silicon Labs	SI8645BB-B-IS Silicon Labs, PCB SMT, 4-Channel Digital Isolator 150Mbps, 2.5 kV, 16-Pin SOIC	
...	TMP125AIDBVR	Texas Instruments	±2°C 2.7V to 5.5V digital temperature sensor with SPI interface and -40 to 125°C o	

Figure 6.2: Schematic/Footprint Examples

You can search for parts in the search fields for the different databases to try to find a part that has a schematic symbol and footprint available. You can see in Figure 6.2 that parts with the symbol and footprint available will have an amp and chip symbol next to them. The box means there is a 3D CAD model associated with them too. If you cannot find the symbol and footprint for a part, we recommend going on Mouser and finding the part, then requesting the symbol and footprint. Usually, the schematic and footprint will be added to SamacSys after a couple of days.

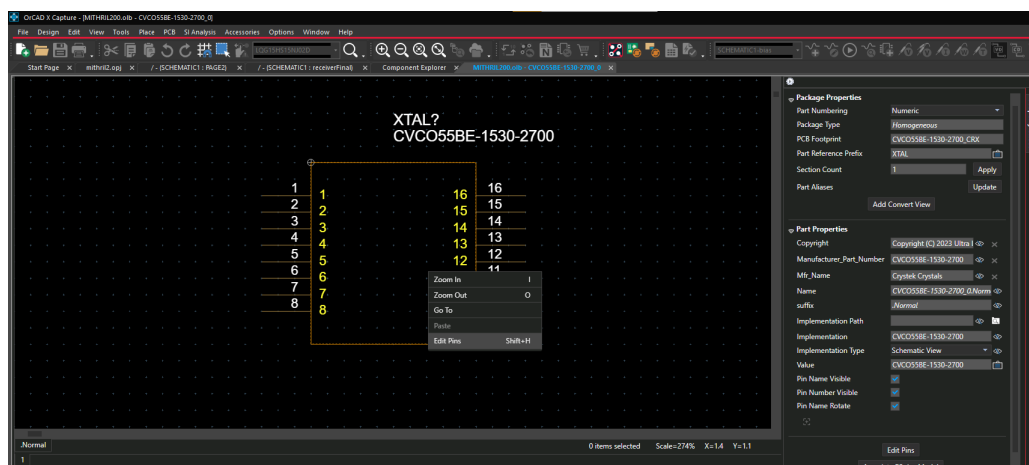


Figure 6.3: Editing Schematic Parts

Sometimes, these symbols and footprints are not correct. If the schematic symbol is incorrectly labeled, you can edit the part, then click edit pins to make sure all the pins are correctly labeled and numbered as can be seen in Figure 6.3.

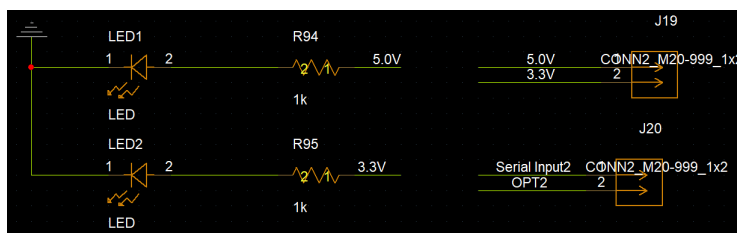


Figure 6.4: Wires and Net Alias

Once you've placed your parts down in the schematic, now comes time to connect everything together. To navigate through the schematic interface, you can use CTRL+Scroll Wheel to zoom in and out, and middle mouse button to scroll left to right.



You can use "w" to enter wiring mode, which lets you place down wires according to your grid size. After wiring, be sure to use "n" to enter net alias mode and assign aliases to your wires. As can be seen in Figure 6.4, there are two non-connected wires both with the alias "5.0V". This effectively connects them since they are under the same alias and will also label them in the layout when routing. Using the net alias helps with things like power where connecting everything that needs power with a wire to your power source would make the schematic a mess. In short, all wires with the same net alias are considered connected.

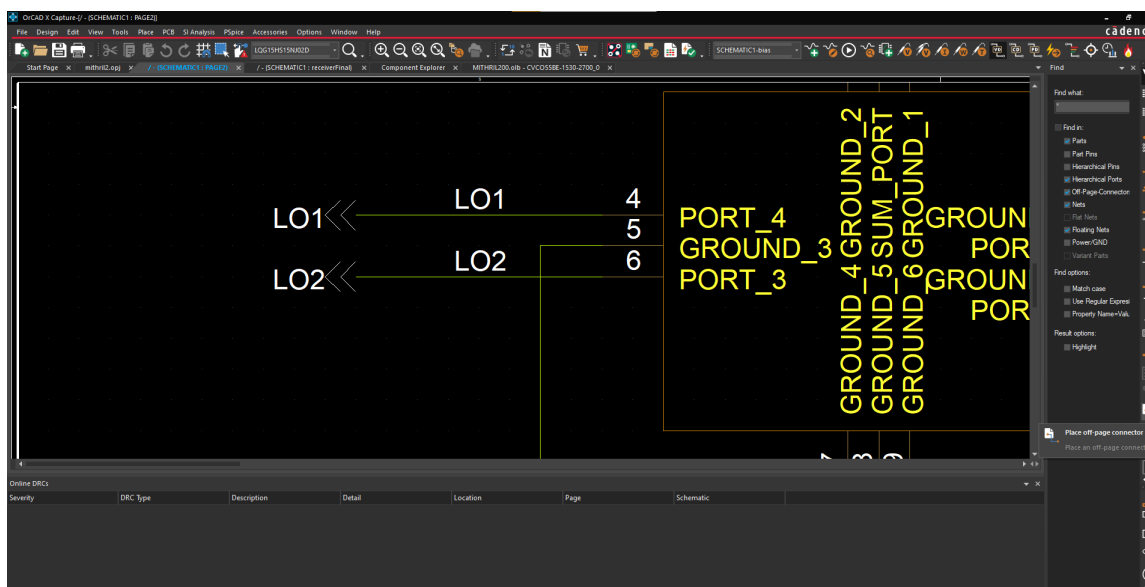


Figure 6.5: Off Page Connectors

If you run out of room or want to separate your schematics into different pages, you can connect wires from different schematic pages using off-page connectors as shown in Figure 6.5. Connect the off-page connector to a wire and name it the same on both schematic pages to have the wires connect.

## 6.1.2 Circuitry Good Practices

### DC Blocking and Coupling Caps

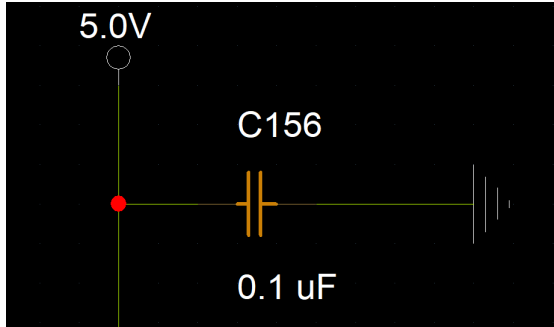


Figure 6.6: Coupling Capacitor

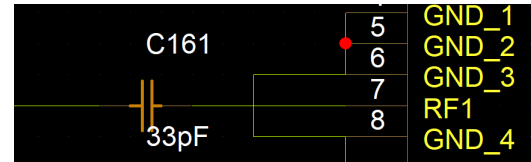


Figure 6.7: DC Blocking Capacitor

Two good practices to include in your schematics are coupling and DC blocking capacitors.

Coupling capacitors are usually used when giving power to some component or chip as can be seen in Figure 6.6. It can be thought of as a mini low-pass filter, where the capacitance of your coupling capacitor will affect the cutoff frequency of the filter. These coupling capacitors should be placed in parallel with the power wire that goes into the chip.

DC Blocking capacitors do the exact opposite, and are usually used when passing a signal from one component to another as can be seen in Figure 6.7. They can be thought of as mini high-pass filters, where the capacitance of the DC Blocking capacitor affects the cutoff frequency. These are placed in series with the signal wire.

$$C = \frac{1}{2\pi X f} \quad (6.1)$$

Figure 6.8: Capacitance of a Coupling or DC Blocking Capacitor

The equation for finding the capacitance of either the coupling or DC blocking capacitor can be seen in Equation 6.8 where  $C$  is the capacitance,  $X$  is the impedance, and  $f$  is the cutoff frequency. Essentially, a higher cutoff frequency corresponds to a lower capacitance value, and the only difference between the coupling and DC blocking capacitor is the coupling capacitor passes everything below that cutoff frequency, and the DC blocking capacitor passes everything above that cutoff frequency.

## Test Pins and Grounds

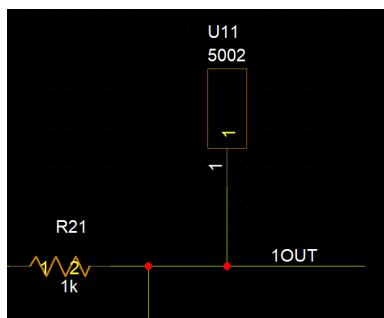


Figure 6.9: Test Pin

Other extremely important things to add are test pins as seen in Figure 6.9 and exposures to ground. Credit to Professor Muresan for telling us to add both of these as they were vital to testing and the operation of the board.

Test pins should be placed in parallel with signal wires so that you can hook in with an oscilloscope and examine what is happening. Really, after every stage in a signal chain it would be good practice to expose the signal via a test pin or if it is RF with an SMA connector. This allows you to debug analog things and find out how each stage is affecting your signal. We only added it in one place and after the fact wished we had placed more test pins so we could see what was happening from component to component.

Ground pins and pads are also really important. We overlooked adding a ground pin which was extremely inconvenient for us, and wished we had put ample ground pins and pads everywhere on the board. These are necessary if using external components with the board, since they should have a common ground.

## Power LEDs

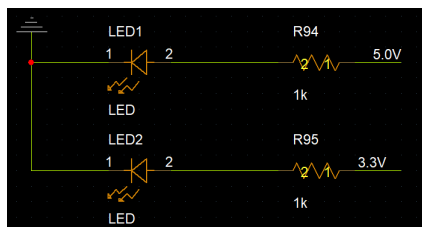


Figure 6.10: Power LEDs

Another nice thing to have are some LEDs connected to power, just so you know at the very least your board is turned on and everything is receiving power. Having a switch of some sort to block power is also something nice to have which we did not add.

## Potentiometers

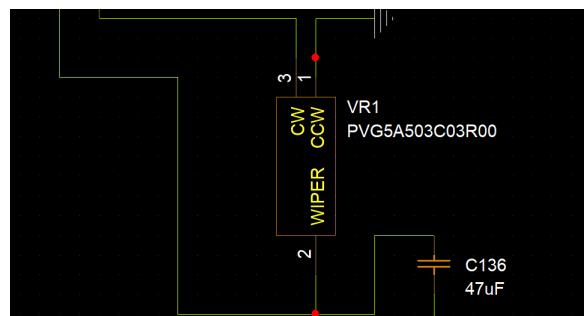


Figure 6.11: Potentiometers

Another extremely useful thing to add is potentiometers, as can be seen in Figure 6.11. In things like amplifying or filtering stages where resistors can change the cutoff frequency or gain of your circuit, potentiometers are very useful. From Figure 6.11, we can see that potentiometers have three ports: CCW, CW, and Wiper. How potentiometers work is that the wiper controls the resistance of the potentiometer, and turning it CW will make more signal go in that port, and turning it CCW will make more signal go into that port (oversimplified explanation). Therefore, it can be set up by just feeding the input to the wiper, the output to CCW, and CW to ground. This can help with changing gains and cutoff frequencies even after the board is printed and assembled.

### 6.1.3 Transmitter

### 6.1.4 Receiver

## 6.2 Layout

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